

FIG. 1

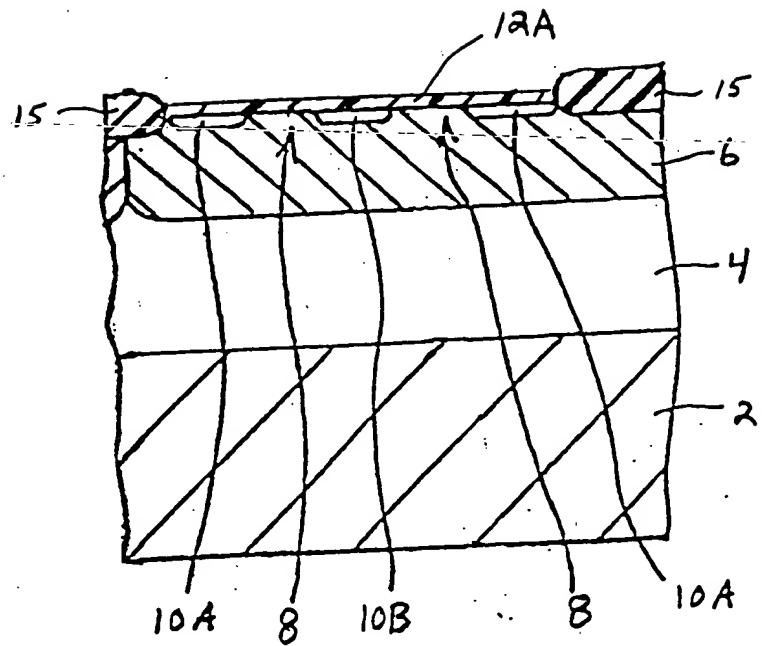


FIG. 2

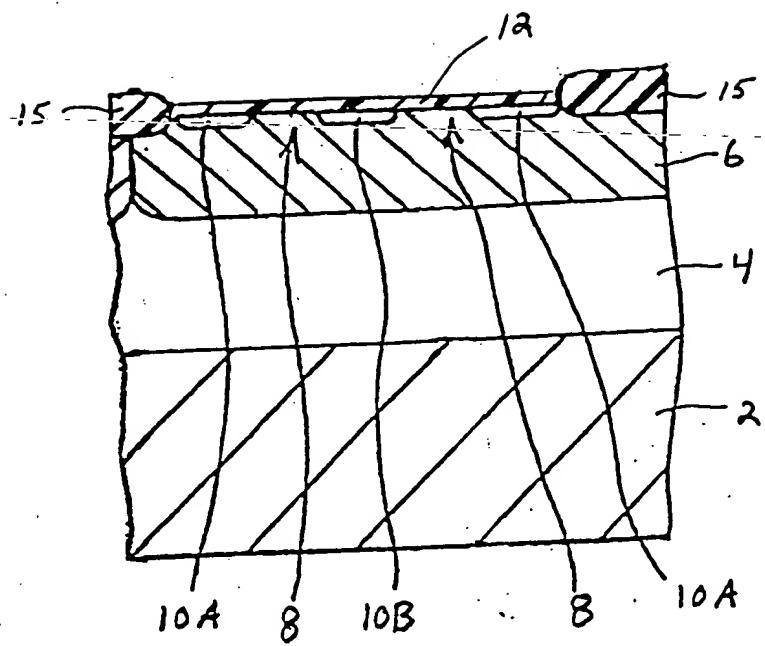


FIG. 3

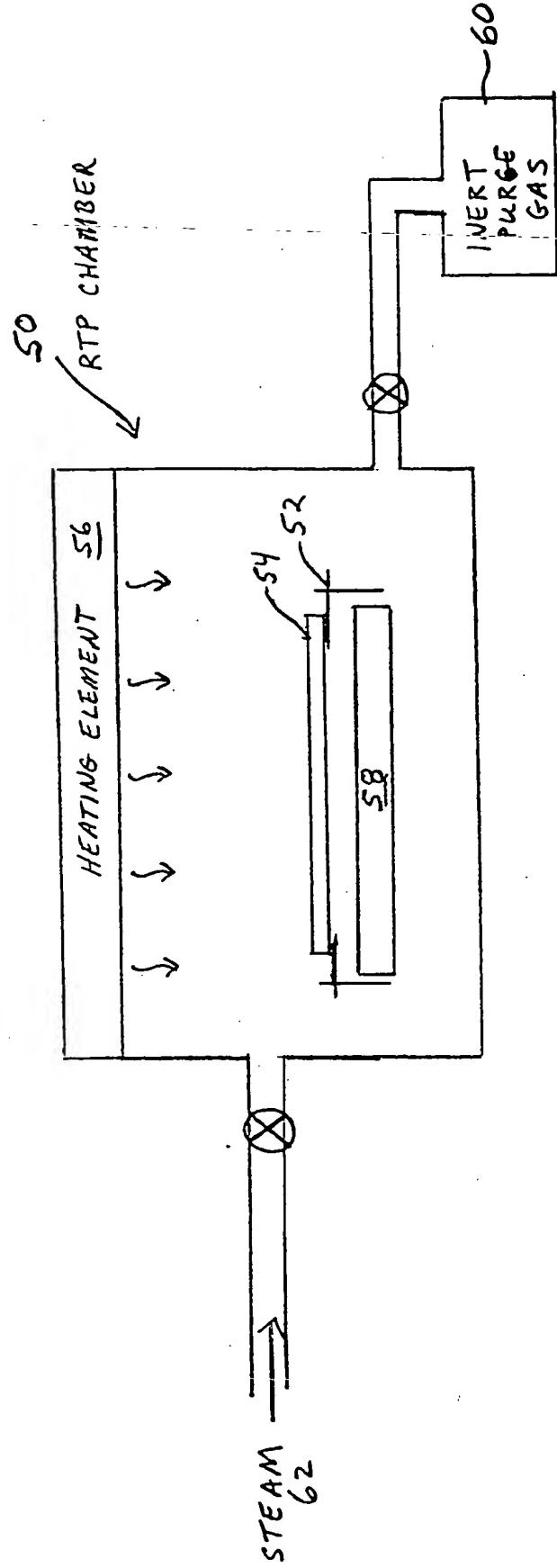


FIG. 4

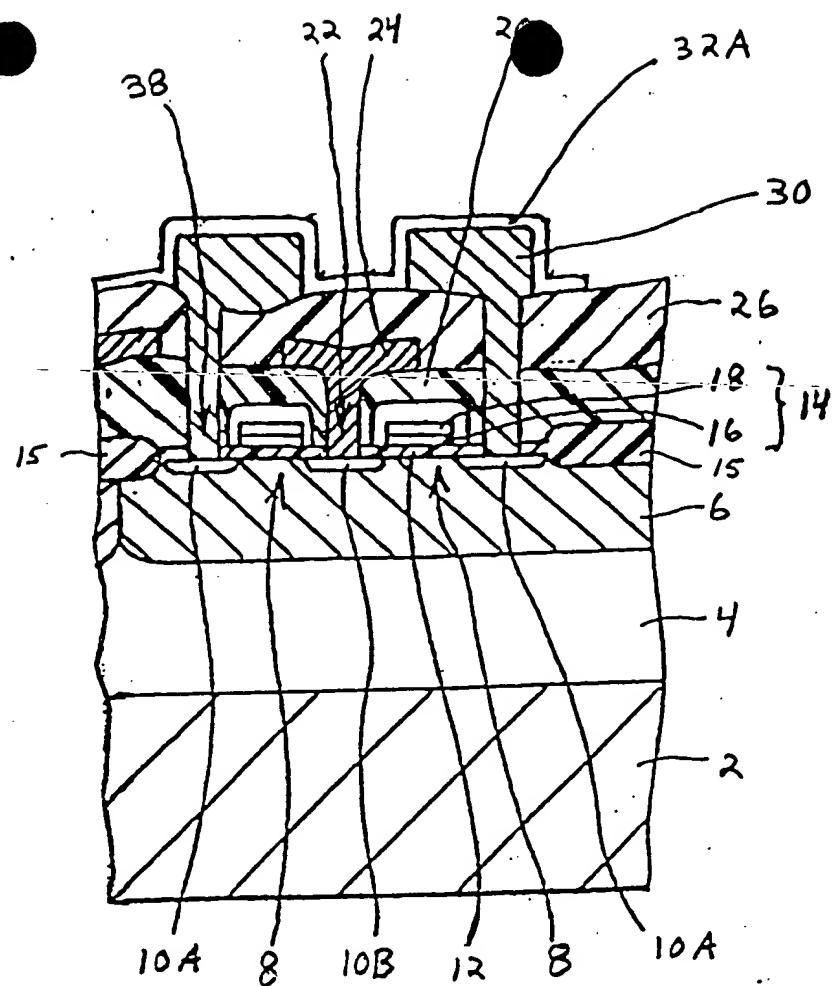


FIG. 5

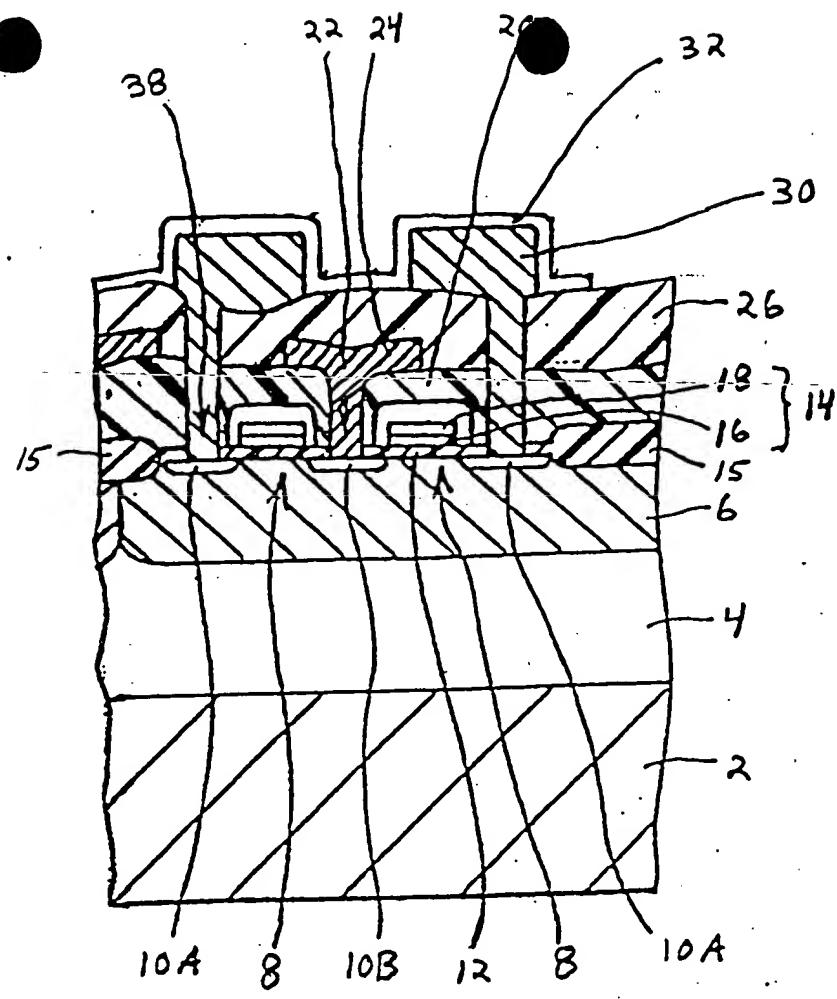


FIG. 6

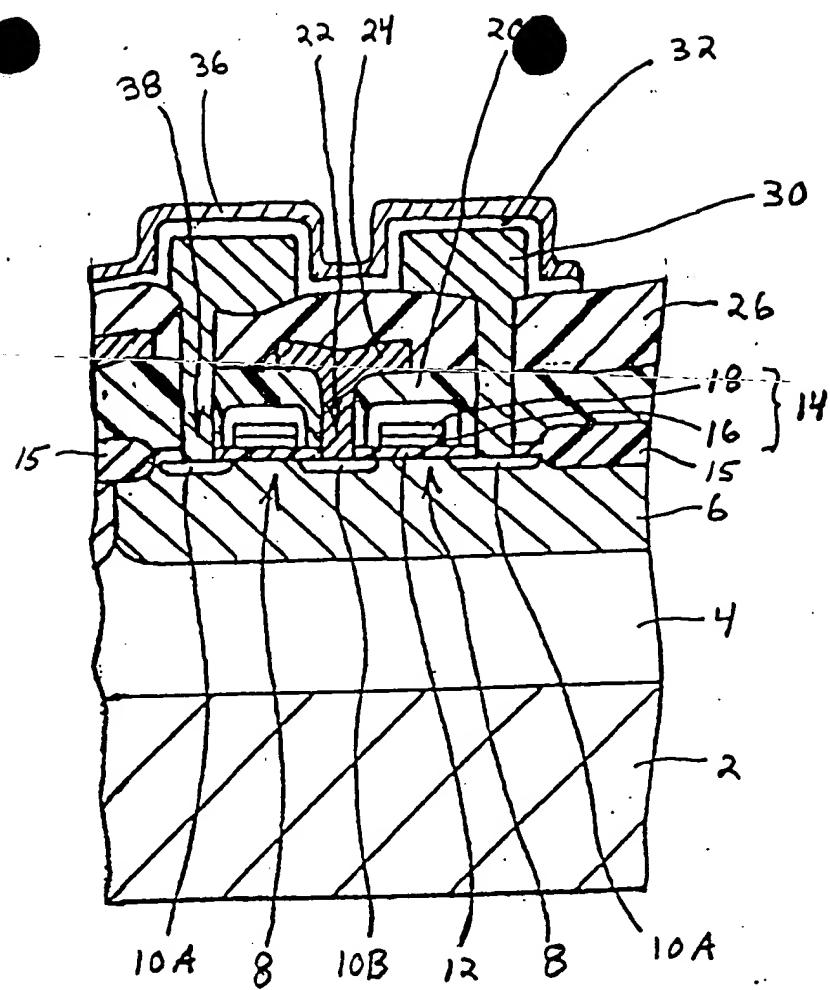


FIG. 7

DEPOSIT DIELECTRIC OR INSULATING FILM



SUBJECT THE INSULATING FILM TO A HEAT TREATMENT IN AN AMBIENT COMPRISING A STABILIZING GAS INCLUDING A GAS SELECTED FROM THE GROUP CONSISTING OF N<sub>2</sub>, O<sub>2</sub>, O<sub>3</sub>, NO, OR N<sub>2</sub>O



SUBJECT THE INSULATING FILM TO A WET OXIDATION IN A RAPID THERMAL PROCESS (RTP) CHAMBER

FIG. 8